



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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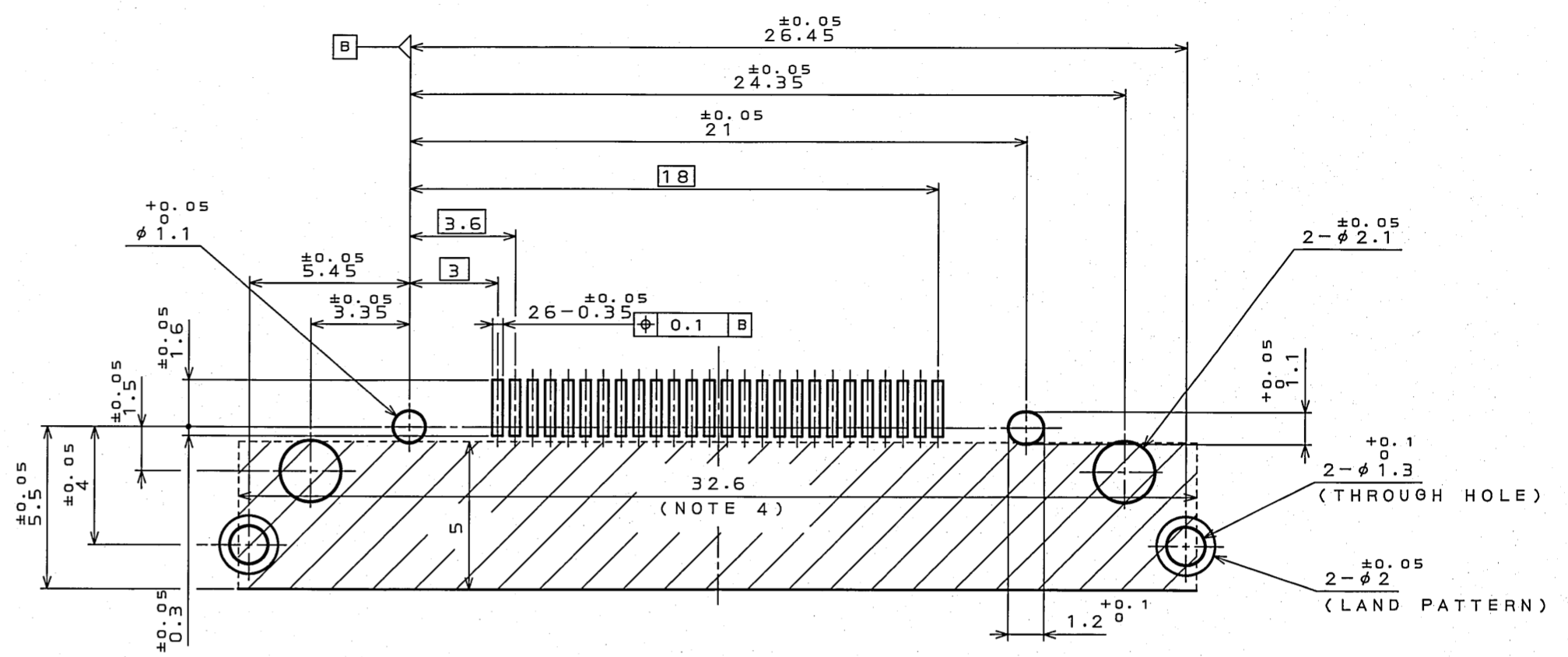
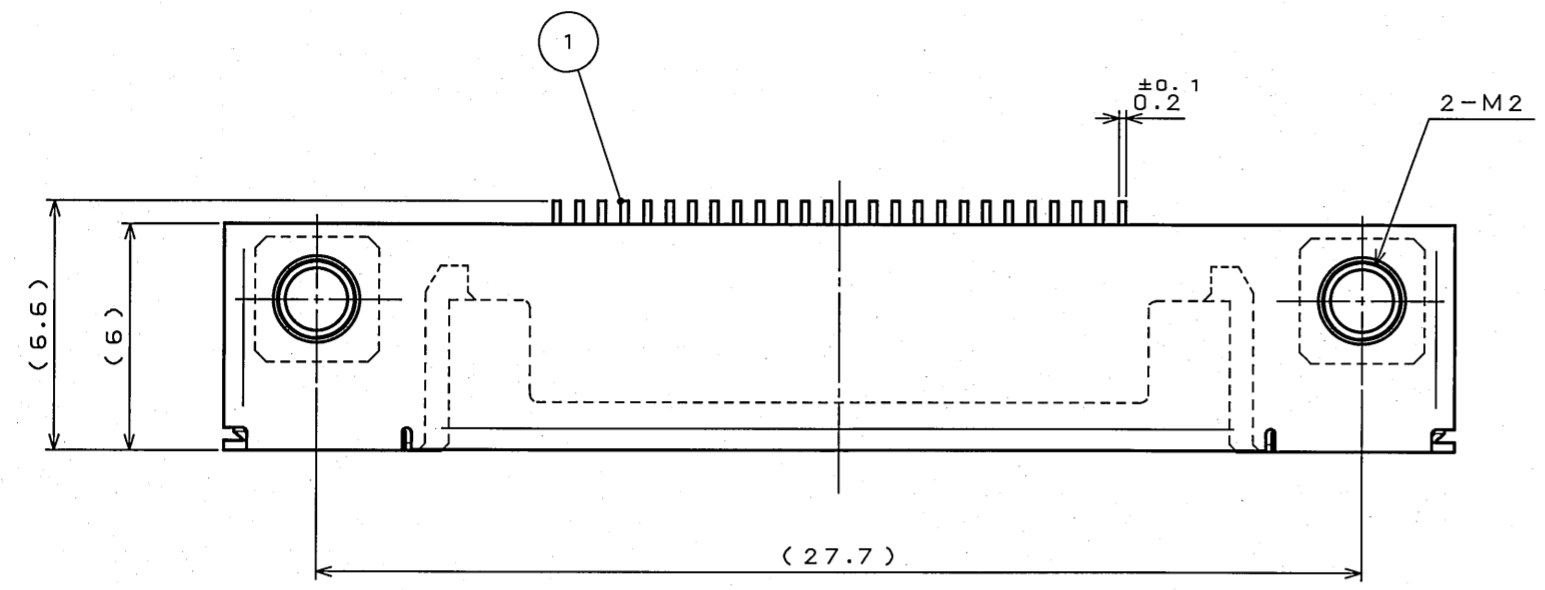
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

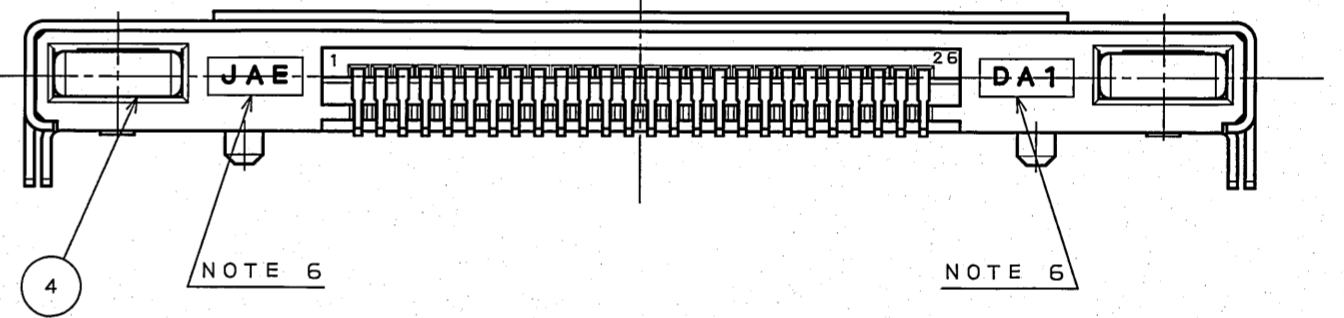
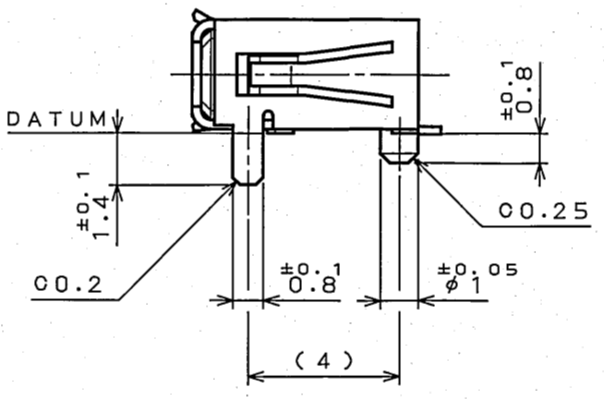
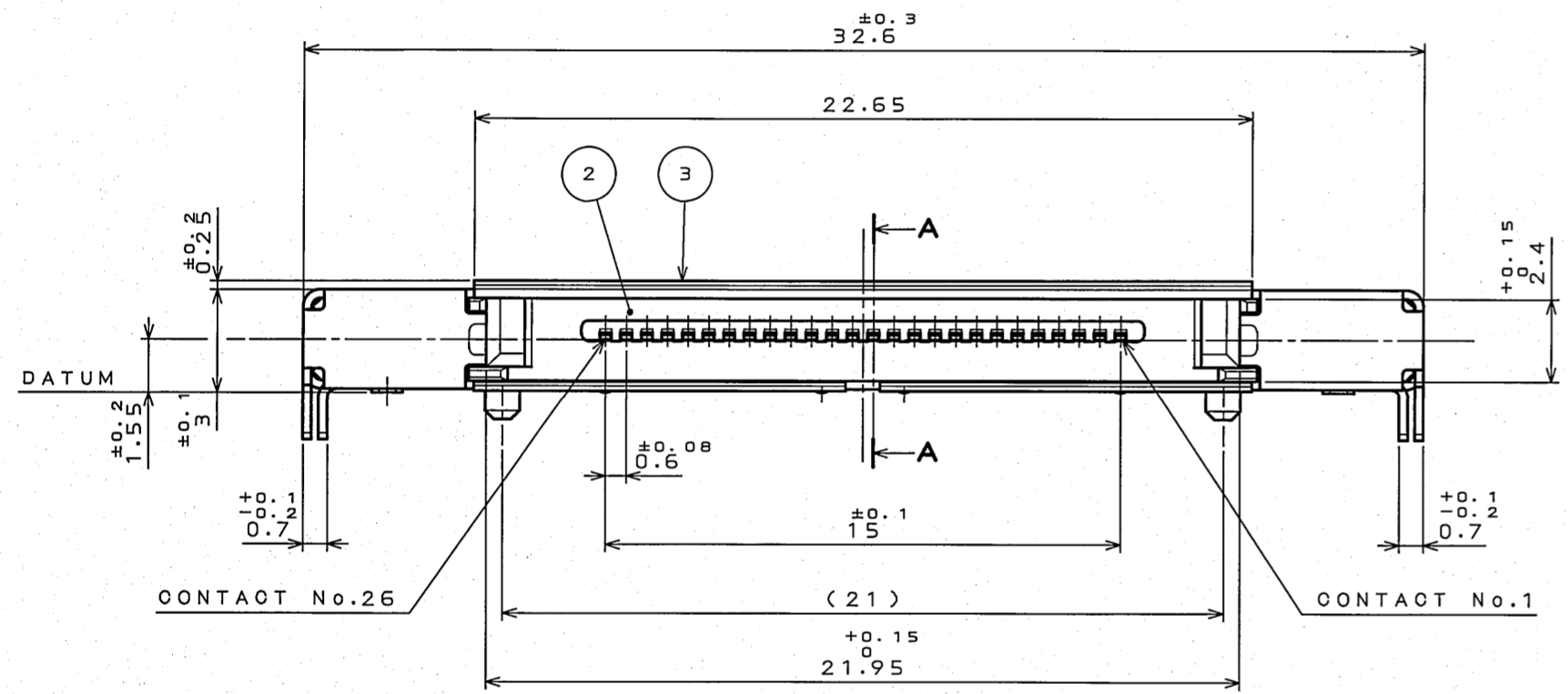


SJ038459  
図面番号(DRAWING NO.)

版数 REV.	年月日 DATE	CON NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
2	16.Dec.2004	056414	FINISH CHANGE、OTHERS		Y.TAKAGI	-	<i>[Signature]</i>



APPLICABLE P.O.B DIMENSION(REF.)(SCALE 5:1)



NOTE1. ⊕ AND ⊙ DENOTE ARE DIRECTION OF SMT TOLERANCE. TERMINAL DIMENSION IS  $0^{+0.05}$ <sub>-0.1</sub> AND DEVIATION (DIMENSION BETWEEN MINUS VALUE & PLUS VALUE) SHALL BE 0.1 MAX.

△ 2. THE CONNECTING AREA IS PLATED WITH GOLD FLASH (0.03 μm MIN) OVER Pd-Ni (0.4 μm MIN) OVER NICKEL (1.5 μm MIN). THE TERMINAL AREA IS PLATED WITH GOLD FLASH (0.03 μm MIN) OVER NICKEL (1.5 μm MIN).

3. THE SHEARED EDGES OF CONNECTOR SHELL AT THE SOLDER AREA ARE NOT PLATING.

4. PLEASE NO PATTERNING IN SLANT AREA.

5. LAND MARK BOTH SIDES OF P.O.B. HOLE OF φ1.1 IS THROUGH HOLE PLATED.

6. COMPANY LOGO "JAE" AND PART NUMBER "DA1" ARE MARKED AS INDICATED.

注1. SMT公差部のプラス、マイナスの方向を示す。端子寸法は  $0^{+0.05}$ <sub>-0.1</sub> であり公差内におけるバラツキ (1コネクタ内のMAX値とMIN値の差) は、0.1以下とする。

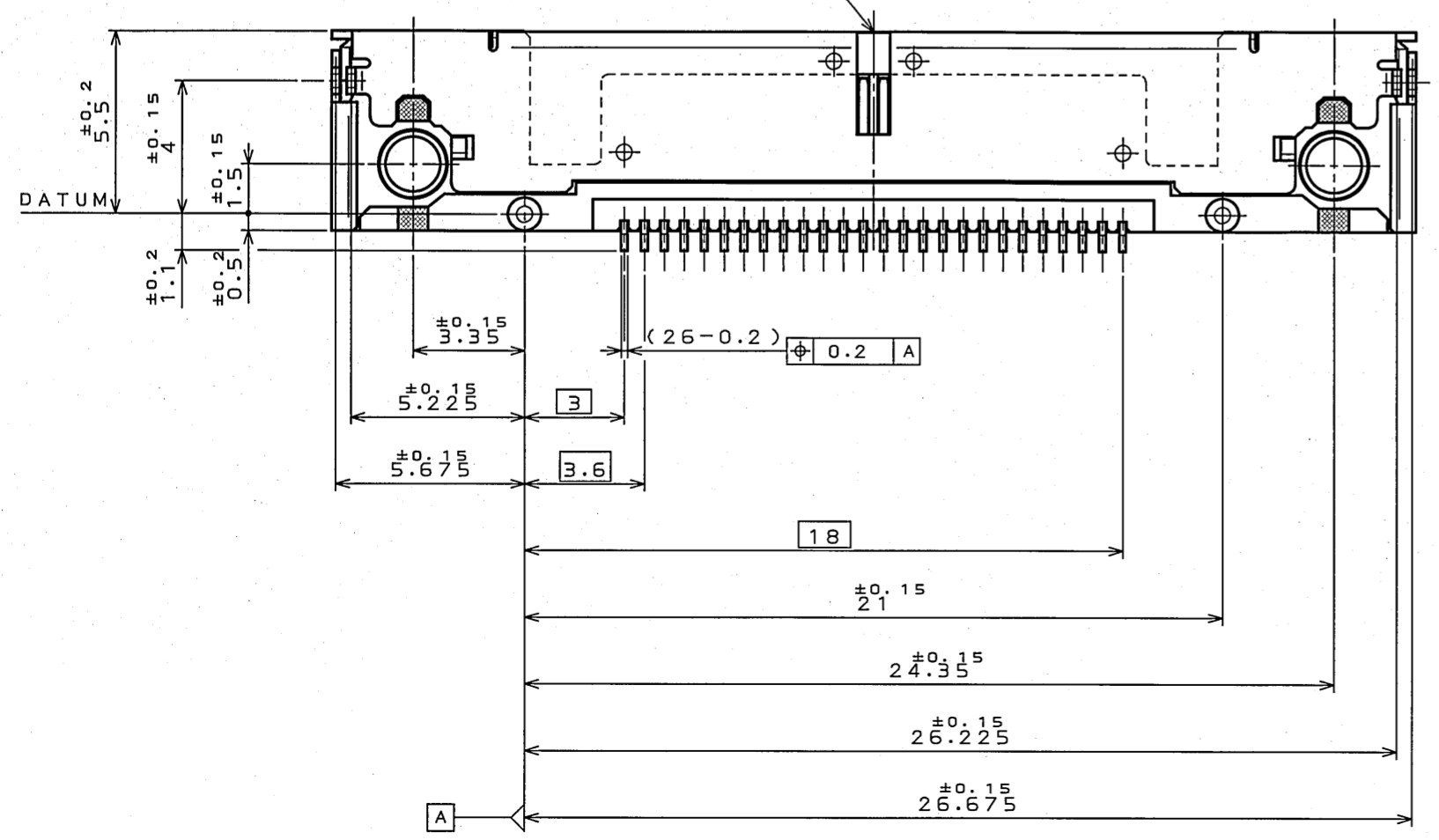
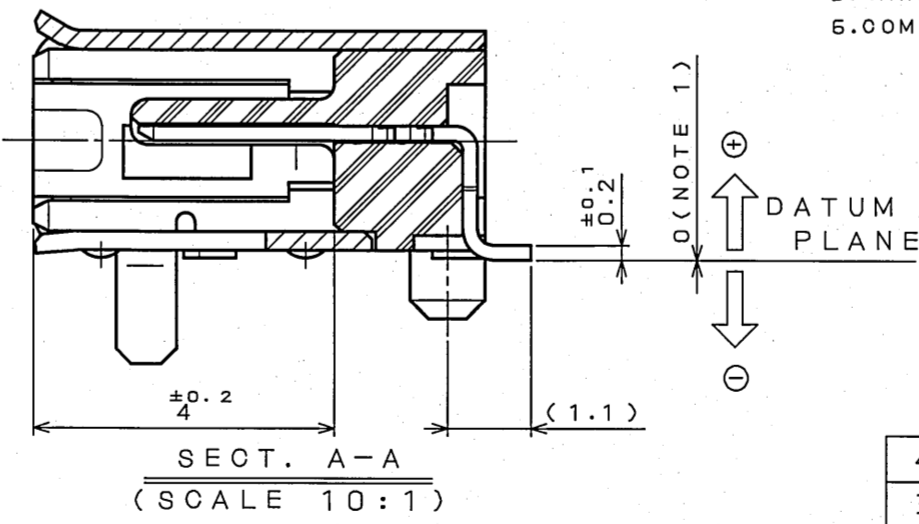
△ 2. 接続部は、ニッケル (1.5 μm 以上) 上パラジウムニッケル (0.4 μm 以上) 上金フラッシュメッキ (0.03 μm 以上) 結線部は、ニッケル (1.5 μm 以上) 上金フラッシュメッキ (0.03 μm 以上) である。

3. 本コネクタシェル半田付部破断面には、メッキは施されません。

4. 本斜線部内にはパターンを配線しないよう願います。

5. ランドは基板の両面に設けること。又、φ1.3の穴はスルーホールメッキであること。

6. 図示の位置に社標 "JAE" 及び品名 "DA1" を表示する。



数量	部名	材料	仕上げ	備考
4	NUT	STEEL	NICKEL PLATING	M2
3	SHELL	1 STAINLESS STEEL	(LEAD FREE) TIN/TIN ALLOY	
2	INSULATOR	1 PPS		UL94 V-0
1	CONTACT	26 COPPER ALLOY	NOTE 2	

符号 NO. JA03-3192	個数 1	材料 3.Mar.2003	仕上げ DA1	備考 日本航空電子工業株式会社
仕様書 (SPECIFICATION)	第1版 (ORIGINAL DATE)	尺 (SCALE)	シリーズ (SERIES)	名称 (TITLE)
DA1R026L91E	3.Mar.2003	5:1	DA1	DA1R026L91E
製図 DR. E.MURANO	担当 CHK. Y.TAKAGI	製図 DR. Y.TAKAGI	承認 APPD. Y.KUBOTA	数量 (MASS)